PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3440857

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUKO OTANI	06/09/2015
SHUNJI MAEDA	06/19/2015
YUTA URANO	06/09/2015
TOSHIFUMI HONDA	06/29/2015
TAKEHIRO HIRAI	06/11/2015
SATORU TAKAHASHI	06/18/2015
KIYOSHI TAKAMASU	06/15/2015

RECEIVING PARTY DATA

Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI SHIMBASHI 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Name:	THE UNIVERSITY OF TOKYO
Street Address:	3-1, HONGO 7-CHOME
City:	BUNKYO-KU, TOKYO
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14799741

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	XA-12927/T9094-21764US01
NAME OF SUBMITTER:	CHERRISE TEXIDOR
SIGNATURE:	/Cherrise Texidor/
DATE SIGNED:	07/15/2015

Total Attachments: 5
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ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by
Hitachi High-Technologies Corporation and The University of Tokyo
a corporation organized under the laws of Japan,
located at
24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan and
3-1, Hongo 7-chome, Bunkyo-ku, Tokyo, Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said
Hitachi High-Technologies Corporation and The University of Tokyo
its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD FOR REVIEWING A DEFECT AND APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Hitachi High-Technologies Corporation and The University of Tokyo
its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation and The University of Tokyo.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) Yuko Otani — Yuko OTANI	Jun. 9, 2015
2) Shunji MAEDA	
3) Yuta Urano — Yuta URANO	Jun. 9, 2015
4) Toshifumi HONDA	
5) Takehiro HIRAI	
6) Satoru TAKAHASHI	
7) Kiyoshi TAKAMASU	

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	INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1)	Yuko OTANI	
2)	Shunji Maeda Shunji MAEDA	June, 19, 2015
3)	Yuta URANO	
4)	Toshifumi HONDA	
5)	Takehiro HIRAI	
6)	Satoru TAKAHASHI	
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1)	Yuko OTANI	
2)	Shunji MAEDA	
3)	Yuta URANO	
4)	Toshifumi Honda Toshifumi HONDA	29 June 2015
5)	Takehiro HIRAI	
6)	Satoru TAKAHASHI	
7)	Kiyoshi TAKAMASU	

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1)	Yuko OTANI	
2)	Shunji MAEDA	
3)	Yuta URANO	
4)	Toshifumi HONDA	
5)	Takehiro Hirai Takehiro HIRAI	June. 11. 2015
6)	Satoru TAKAHASHI	
7)	Kiyoshi TAKAMASU	

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5) Takehiro HIRAI	
6) X 高橋 悟 Satoru Takahashi X Satoru TAKAHASHI	X 18 June 2015 X
7) X Kiyoshi X Kiyoshi TAKAMASU	X 15 June 2015 X